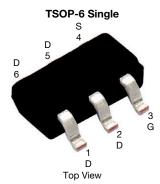
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RoHS

COMPLIANT



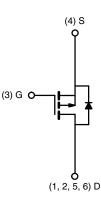
FEATURES

P-Channel 30 V (D-S) MOSFET

- TrenchFET® power MOSFET
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

Load switch



P-Channel MOSFET

Marking code: AT

PRODUCT SUMMARY					
V _{DS} (V)	-30				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -10 V	0.074				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -4.5 V	0.113				
Q _g typ. (nC)	5.1				
I _D (A) ^a	-5.1				
Configuration	Single				

ORDERING INFORMATION

Package	TSOP-6
Lead (Pb)-free	Si3457CDV-T1-E3
Lead (Pb)-free and halogen-free	Si3457CDV-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25 \degree C$, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	-30	V	
Gate-source voltage		V _{GS}	± 20	v	
	T _C = 25 °C		-5.1		
Continuous drain ourrent (T 150 °C)	T _C = 70 °C		-4.1		
Continuous drain current ($T_J = 150 \ ^{\circ}C$)	T _A = 25 °C	I _D	-4.1 ^{b, c}		
	T _A = 70 °C	1	-3.3 ^{b, c}	A	
Pulsed drain current		I _{DM}	-20		
Cantinuaus source drain diade surrent	T _C = 25 °C		-2.5		
Continuous source-drain diode current	T _A = 25 °C	I _S	-1.67 ^{b, c}		
	T _C = 25 °C		3		
Maximum power dissipation	T _C = 70 °C		2	14/	
	T _A = 25 °C	PD	2 ^{b, c}	W	
	T _A = 70 °C	1	1.3 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stq}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient b, d	t ≤ 5 s	R _{thJA}	55	62.5	°C/W
Maximum junction-to-foot (drain)	Steady state	R _{thJF}	34	41	C/ VV

Notes

a. Based on $T_C = 25 \ ^{\circ}C$

b. Surface mounted on 1" x 1" FR4 board

c. t = 5 s

d. Maximum under steady state conditions is 110 °C/W

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Si3457CDV

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PARAMETER SYMBOL TEST CONDITIONS		TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static			•			•
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-30	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	1 050 A	-	-31	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	4.5	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	-1	-	-3	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	-	-	± 100	nA
7		$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	-1	μA
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$	-	-	-10	
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	-20	-	-	A
D · · · · · · · ·		$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -4.1 \text{ A}$	-	0.060	0.074	
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -4.5 V, I _D = -1 A	-	0.092	0.113	Ω
Forward transconductance ^a	9 _{fs}	V _{DS} = -15 V, I _D = -4.1 A	-	8	-	S
Dynamic ^b	· ·					
Input capacitance	C _{iss}		-	450	-	
Output capacitance	C _{oss}	V _{DS} = -15 V, V _{GS} = 0 V, f = 1 MHz	-	80	-	pF
Reverse transfer capacitance	C _{rss}		-	63	-	
·	Qg	$V_{DS} = -15 \text{ V}, \text{ V}_{GS} = -10 \text{ V}, \text{ I}_{D} = -4.1 \text{ A}$	-	10	15	
Total gate charge			-	5.1	8	nC
Gate-source charge	Q _{gs}	V_{DS} = -15 V, V_{GS} = -4.5 V, I_{D} = -4.1 A	-	1.8	-	
Gate-drain charge	Q _{gd}		-	2.5	-	
Gate resistance	R _q	f = 1 MHz	-	7	-	Ω
Turn-on delay time	t _{d(on)}		-	40	60	-
Rise time	tr	$V_{DD} = -15 \text{ V}, \text{ R}_{\text{I}} = 4.6 \Omega$	-	80	120	
Turn-off delay time	t _{d(off)}	$I_D \cong -3.3$ Å, $V_{GEN} = -4.5$ V, $R_g = 1$ Ω	-	20	30	1
Fall time	t _f		-	12	20	
Turn-on delay time	t _{d(on)}		-	5	10	ns
Rise time	t _r	$V_{DD} = -15 \text{ V}, \text{ R}_{\text{I}} = 4.6 \Omega$	-	13	20	1
Turn-off delay time	t _{d(off)}	$I_D \cong$ -3.3 A, V_{GEN} = -10 V, R_g = 1 Ω	-	20	30	
Fall time	t _f		-	10	15	
Drain-Source Body Diode Characterist	ics		•		•	
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-2.5	
Pulse diode forward current ^a	I _{SM}		-	-	-20	A
Body diode voltage	V _{SD}	I _S = -3.3 A	-	-0.8	-1.2	V
Body diode reverse recovery time	t _{rr}	-	-	20	30	ns
Body diode reverse recovery charge	Q _{rr}	I _F = -3.3 A, di/dt = 100 A/μs,	-	20	30	nC
Reverse recovery fall time	ta	$T_J = 25 \text{ °C}$	-	14	-	
Reverse recovery rise time	t _b		-	6	<u> </u>	ns

Notes

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

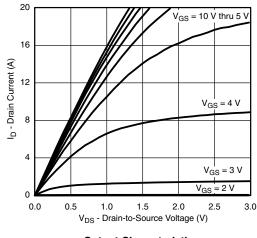
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

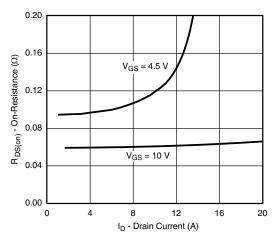


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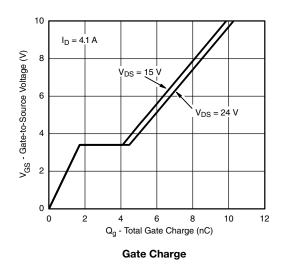
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

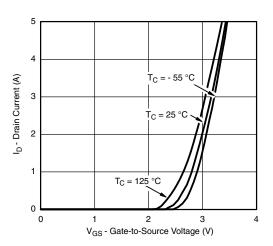




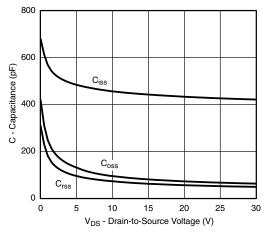


On-Resistance vs. Drain Current and Gate Voltage

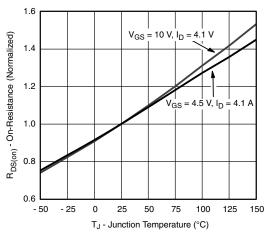




Transfer Characteristics







On-Resistance vs. Junction Temperature

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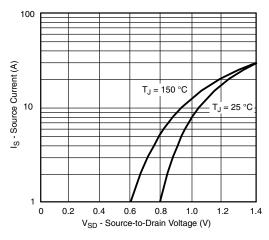
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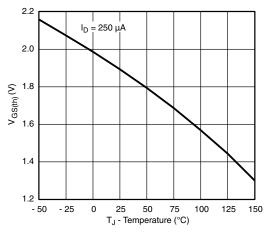


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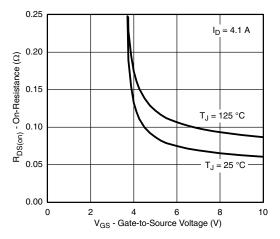
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



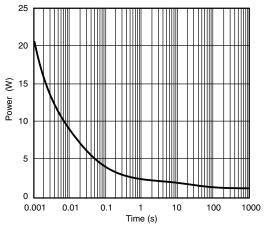
Source-Drain Diode Forward Voltage



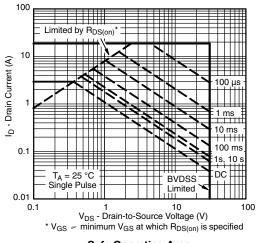




On-Resistance vs. Gate-to-Source Voltage



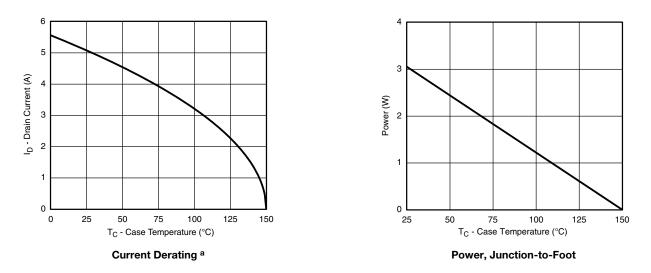






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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



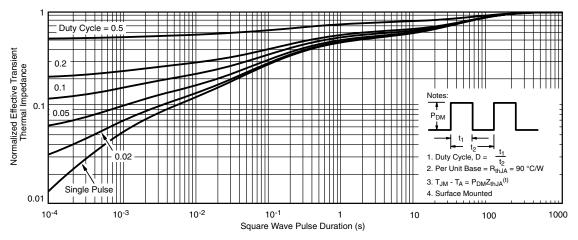
Notes

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

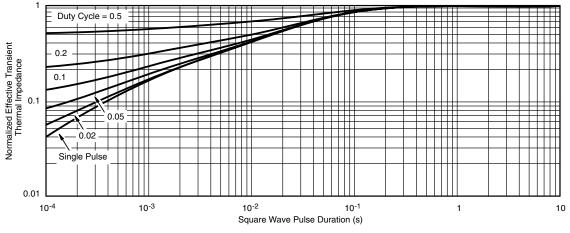


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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Package Information

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TSOP: 5/6-LEAD JEDEC Part Number: MO-193C









6-LEAD TSOP



	MILLIMETERS			INCHES					
Dim	Min	Nom	Max	Min	Nom	Max			
Α	0.91	-	1.10	0.036	-	0.043			
A ₁	0.01	-	0.10	0.0004	-	0.004			
A ₂	0.90	-	1.00	0.035	0.038	0.039			
b	0.30	0.32	0.45	0.012	0.013	0.018			
С	0.10	0.15	0.20	0.004	0.006	0.008			
D	2.95	3.05	3.10	0.116	0.120	0.122			
Е	2.70	2.85	2.98	0.106	0.112	0.117			
E ₁	1.55	1.65	1.70	0.061	0.065	0.067			
е		0.95 BSC			0.0374 BSC				
e ₁	1.80	1.90	2.00	0.071	0.075	0.079			
L	0.32	-	0.50	0.012	-	0.020			
L ₁		0.60 Ref			0.024 Ref				
L ₂	0.25 BSC				0.010 BSC				
R	0.10	-	-	0.004	-	-			
θ	0°	4°	8°	0°	4°	8°			
θ_1	7° Nom				7° Nom				
		ev. I, 18-Dec	c-06			ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540			

PAD Pattern



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Recommended Land Pattern For TSOP-5L / TSOP-6L





TSOP 5L





Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022	
DWG: 3010	



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